imall

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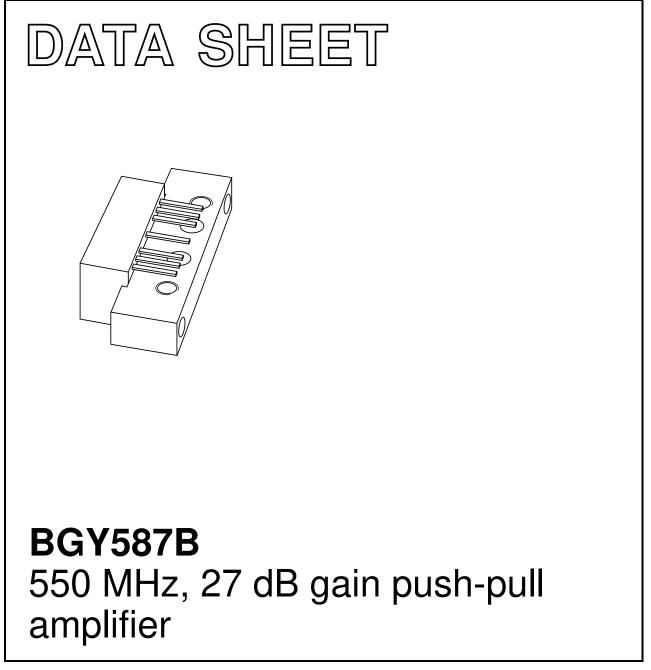


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DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1997 Apr 10 2001 Oct 22



2001 Oct 22

FEATURES

- Excellent linearity
- Extremely low noise

NXP Semiconductors

- Silicon nitride passivation
- Rugged construction
- TiPtAu metallized crystals ensure optimal reliability.

DESCRIPTION

SYMBOL

LIMITING VALUES

SYMBOL

Gp

I_{tot}

Vi

T_{stg}

T_{mb}

 V_{B}

Hybrid amplifier module for CATV systems operating over a frequency range of 40 to 550 MHz at a voltage supply of +24 V (DC).

power gain

RF input voltage

storage temperature

DC supply voltage

PARAMETER

total current consumption (DC)

In accordance with the Absolute Maximum Rating System (IEC 60134).

operating mounting base temperature

QUICK REFERENCE DATA

PINNING	-	SO	T1	1	5J

PIN	DESCRIPTION	
1	input	
2	common	
3	common	
5	+V _B	
7	common	
8	common	
9	output	

f = 50 MHz

f = 550 MHz

 $V_B = +24 V$

PARAMETER

CONDITIONS

PIN CONFIGURATION

MIN.

MIN.

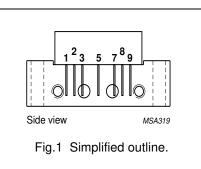
-40

-20

26.2

27.5

_



MAX.

MAX.

55

+100

+100

+28

27.8

340

_

UNIT

UNIT

dBmV

°C

°C

V

dB

dB

mΑ

Product specification

BGY587B

550 MHz, 27 dB gain push-pull amplifier

BGY587B

СНА	RAC	TFR	ISTI	CS
CITA				00

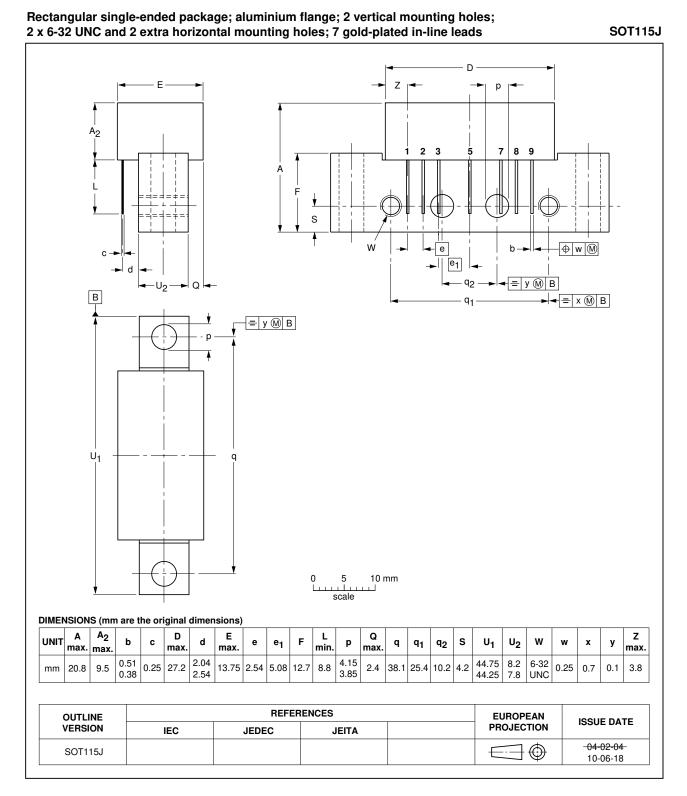
Table 1	Bandwidth 40 to 550 MHz; $T_{case} = 30 \text{ °C}$; $Z_S = Z_L = 75 \Omega$
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SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	26.2	27.8	dB
		f = 550 MHz	27.5		dB
SL	slope cable equivalent	f = 40 to 550 MHz	0.5	2.5	dB
FL	flatness of frequency response	f = 40 to 550 MHz	-	±0.4	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	_	dB
		f = 80 to 160 MHz	19	-	dB
		f = 160 to 550 MHz	18	_	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	_	dB
		f = 80 to 160 MHz	19	-	dB
		f = 160 to 550 MHz	18	_	dB
СТВ	composite triple beat	77 channels flat; $V_0 = 44 \text{ dBmV}$; measured at 547.25 MHz	_	-57	dB
X _{mod}	cross modulation	77 channels flat; $V_o = 44 \text{ dBmV}$; measured at 55.25 MHz	_	-60	dB
CSO	composite second order distortion	77 channels flat; $V_o = 44 \text{ dBmV}$; measured at 548.5 MHz	_	-57	dB
d ₂	second order distortion	note 1	-	-68	dB
Vo	output voltage	d _{im} = -60 dB; note 2	61	_	dBmV
F	noise figure	f = 550 MHz	-	6.5	dB
I _{tot}	total current consumption	DC value; $V_B = +24$ V; note 3	_	340	mA

Notes

- $\begin{array}{ll} \text{1.} & f_p = 55.25 \; \text{MHz}; \; V_p = 44 \; \text{dBmV}; \\ f_q = 493.25 \; \text{MHz}; \; V_q = 44 \; \text{dBmV}; \\ & \text{measured at} \; f_p + f_q = 548.5 \; \text{MHz}. \end{array}$
- 3. The module normally operates at V_B = +24 V, but is able to withstand supply transients up to +30 V.

PACKAGE OUTLINE



BGY587B

BGY587B

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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BGY587B

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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